



#13/Response  
3/27/03  
PATENT  
[Signature]

# IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

## In re Application of:

Kloster, et al.

Serial No.: 09/820,079

Filed: March 28, 2001

For: STRUCTURE IN A  
MICROELECTRONIC DEVICE  
INCLUDING A BI-LAYER FOR A  
DIFFUSION BARRIER AND AN  
ETCH STOP LAYER

Examiner: Thomas J. Magee

Group Art Unit: 2811

Attorney Docket No.: 42390.P11026

## CERTIFICATE OF MAILING

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## RESPONSE AFTER FINAL REJECTION

Box AF  
Hon. Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

This Response After Final Rejection is in response to the Final Office Action mailed January 22, 2003 and is submitted to put the pending case into condition for allowance thereof or into better condition for appeal. Consideration of this response is respectfully requested.